L Number	Hits	Search Text	DB	Time stamp
-	22537	"MEMS"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:57
-	5873	etching and recess and bonding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 10:48
-	240	"MEMS" and (etching and recess and bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 11:03
-	1576	microsensors	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 11:03
-	5488	sacrificial adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 11:04
-	914	"MEMS" and (sacrificial adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 11:04
-	69	microsensors and ("MEMS" and (sacrificial adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 11:04
-	2627	"MEMS" and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:35
-	611590	cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:35
-	744	("MEMS" and mirror) and cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:38
-	10978	substrate and sacrificial	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:39
-	175	(("MEMS" and mirror) and cavity) and (substrate and sacrificial)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:49
-	10114	variable adj capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:49
-	224	"MEMS" and (variable adj capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 10:50

–		0	("200100560618").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:20
–		2	("20010050618").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:20
–		7774	"shin-etsu"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:57
–		30719	wafer and hydrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:58
–		631	"shin-etsu" and (wafer and hydrogen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:58
–		1974	stacking adj faults	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 12:58
–		42	("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 13:10
–		3267641	vacuum or pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 13:12
–		15	(("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/12 13:12